

Description

The AUIRFR2905ZTRL uses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

V_{DS} = 60V I_D =50 A

 $R_{DS(ON)}$ < 15m Ω @ V_{GS} =10V

Application

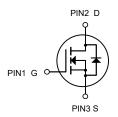
Battery protection

Load switch

Uninterruptible power supply



TO-252-2L (TO-252)



N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
AUIRFR2905ZTRL	TO-252-2L(TO-252)	HXY MOSFET	2500

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units	
VDS	Drain-Source Voltage	60	V	
Vgs	Gate-Source Voltage	±20	V	
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	50	А	
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	25	А	
Ірм	Pulsed Drain Current ²	90	А	
EAS	Single Pulse Avalanche Energy ³	39.2	mJ	
las	Avalanche Current	28	А	
P _D @T _C =25°C	Total Power Dissipation ⁴	45	W	
P _D @T _A =25°C	Total Power Dissipation ⁴	2	W	
Тѕтс	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	
R ₀ JA	Thermal Resistance Junction-Ambient ¹	62	°C/W	
Rejc	Thermal Resistance Junction-Case ¹	2.8	°C/W	



N-Channel Enhancement Mode MOSFET

Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60			V
∆BV _{DSS} /∆T _J	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =1mA		0.057		V/°C
		V _{GS} =10V , I _D =20A		11	15	
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =10A		15	20	mΩ
$V_{\text{GS(th)}}$	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2		2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	- VGS-VDS , ID -230UA		-5.68		mV/°C
		V _{DS} =48V , V _{GS} =0V , T _J =25°C			1	
IDSS	Drain-Source Leakage Current	V _{DS} =48V , V _{GS} =0V , T _J =55°C			5	uA
Igss	Gate-Source Leakage Current	V_{GS} = $\pm 20V$, V_{DS} = $0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =15A		45		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.7		Ω
Qg	Total Gate Charge (4.5V)			19.3		
Qgs	Gate-Source Charge	V _{DS} =48V , V _{GS} =4.5V , I _D =15A		7.1		nC
Q _{gd}	Gate-Drain Charge			7.6		
Td(on)	Turn-On Delay Time			7.2		
Tr	Rise Time	V _{DD} =30V , V _{GS} =10V ,		50		ns
$T_{d(off)}$	Turn-Off Delay Time	_R _G =3.3Ω , _I _D =15A		36.4		
T _f	Fall Time	- IU- IUA		7.6		
Ciss	Input Capacitance			2423		
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		145		pF
Crss	Reverse Transfer Capacitance			97		
Is	Continuous Source Current ^{1,5}				35	Α
Іѕм	Pulsed Source Current ^{2,5}	V _G =V _D =0V , Force Current			80	Α
VsD	Diode Forward Voltage ²	V _{GS} =0V , I _S =A , T _J =25°C			1	V
t _{rr}	Reverse Recovery Time	IF-15A dI/d+-100A/uc		16.3		nS
Qrr	Reverse Recovery Charge	IF=15A,dI/dt=100A/μs , T _J =25°C		11		nC

Note:

- 1.The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leqq 300 us$, duty cycle $\leqq 2\%$
- 3.The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=28A
- 4.The power dissipation is limited by 150°C junction temperature 5.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation



Typical Characteristics

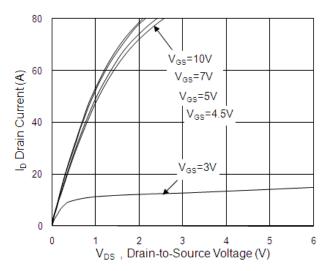


Fig.1 Typical Output Characteristics

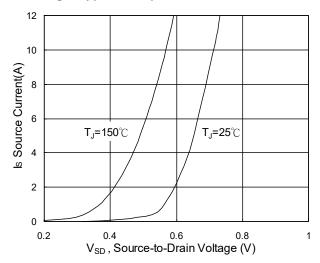


Fig.3 Forward Characteristics of Reverse

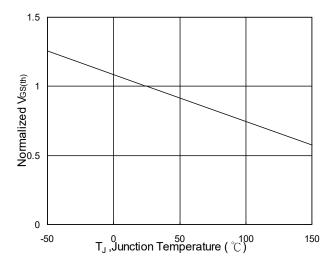


Fig.5 Normalized V_{GS(th)} v.s T_J

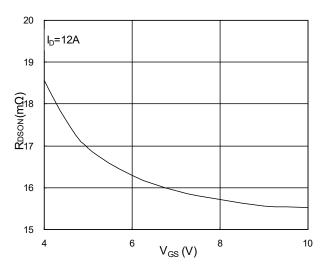


Fig.2 On-Resistance v.s Gate-Source

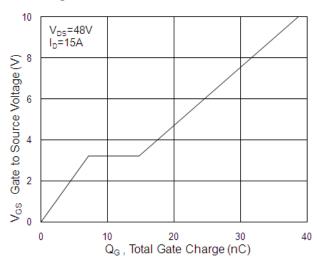


Fig.4 Gate-Charge Characteristics

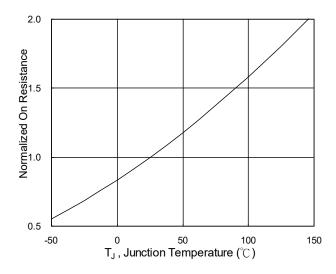
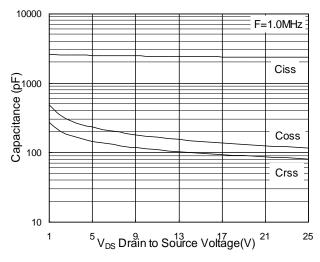


Fig.6 Normalized R_{DSON} v.s T_J



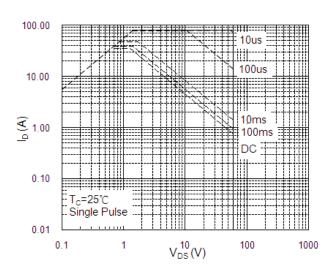


Fig.7 Capacitance

Fig.8 Safe Operating Area

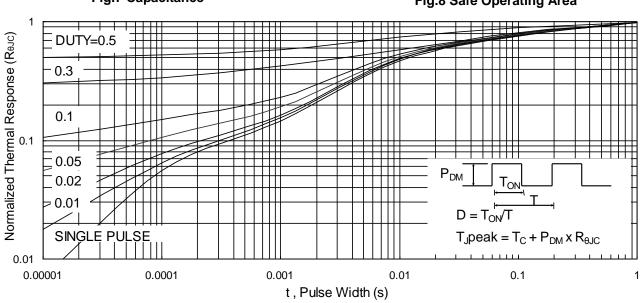


Fig.9 Normalized Maximum Transient Thermal Impedance

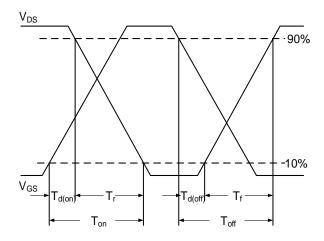


Fig.10 Switching Time Waveform

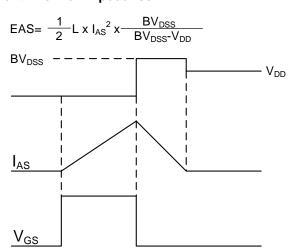
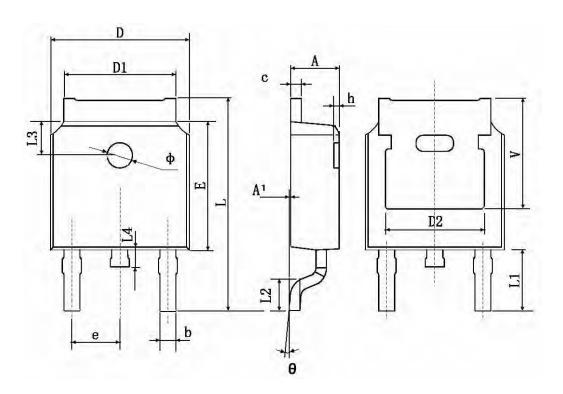


Fig.11 Unclamped Inductive Switching Waveform

N-Channel Enhancement Mode MOSFET

TO-252-2L(TO-252) Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350) TYP.	0.211 TYP.		

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